

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Original): A process for producing an electronic component, comprising:
forming a via hole in a base material having a conductor layer on at least one surface thereof
by performing laser irradiation from the other surface side of the base material; forming a
conductor part in the via hole through deposition of plating in the via hole using the
conductor layer as an electrode; and causing an electroless plating to be deposited in the via
hole such that an electroless plating layer in close contact with an inner wall surface of the
via hole extends in the thickness direction of the conductor part.

Claim 2 (Original): A process for producing an electronic component which effects
conduction processing between front and back surfaces of a base material equipped with a
core material and having a conductor layer formed on one surface thereof, the process
comprising: forming a via hole in the base material having the conductor layer by performing
laser irradiation at least from the other surface side of the base material; forming an
electroless plating layer in close contact with an inner wall surface of the via hole after
deposition of a plating until the core material exposed on the inner wall surface of the via
hole is covered by using the conductor layer as an electrode; and depositing a plating again
by using the conductor layer as an electrode to cover the electroless plating layer to thereby
form a conductor part in the via hole.

Claim 3 (Original): A process for producing an electronic component according to
Claim 2, wherein the core material is caused to protrude from the inner wall surface of the via

hole through laser irradiation to thereby form an anchor structure with respect to the conductor part.

Claim 4 (Original): A process for producing an electronic component which effects conduction processing between front and back surfaces of a base material equipped with a core material and having a conductor layer formed on one surface thereof, the process comprising: forming a via hole in the base material having the conductor layer by performing laser irradiation at least from the other surface side of the base material; causing the core material to protrude from an inner wall surface of the via hole; and depositing a plating by using the conductor layer as an electrode so as to form an anchor structure together with the core material protruding from the inner wall surface of the via hole to form a conductor part in the via hole.

Claim 5 (Original): A process for producing an electronic component according to any one of claims 2 through 4, wherein the core material is formed of glass cloth.

Claim 6 (Currently Amended): An electronic component comprising:
a base material with a core material, having a conductor layer on at least one surface thereof;
a via hole, an inner wall surface of which a protusion protudes, formed through laser irradiation from the other surface side of the base material;
a first plating layer formed using the conductor layer as an electrode and that covers the protusion protruding from the inner wall surface of the via hole; and
an electroless plating layer having a part formed on the first plating layer, and a part of which is in close contact with an inner wall surface of the via hole[;]] and

~~a conductor part which covers the electroless plating layer and which is formed in the via hole.~~

Claim 7 (Currently Amended): An electronic component according to claim 6,
further comprising:

~~a base material equipped with a core material and having a conductor layer on at least one surface thereof;~~

~~a via hole formed through laser irradiation from the other surface side of the base material;~~

~~a first plating layer formed by using the conductor layer as an electrode so as to cover the core material, which is exposed on an inner wall surface of the via hole;~~

~~an electroless plating layer which is formed on the upper side of the first plating layer and which is in close contact with the inner wall surface of the via hole; and~~

~~a second plating layer formed by using the conductor layer as an electrode so as to cover the electroless plating layer,~~

wherein a conductor part is formed ~~in the via hole~~ by the first plating layer, the electroless plating layer, and the second plating layer.

Claim 8 (Original): An electronic component according to Claim 7, wherein a protrusion is formed on the inner wall surface of the via hole, the protrusion and the conductor part forming an anchor structure.

Claim 9 (Original): An electronic component according to Claim 8, wherein the protrusion is formed by the core material protruding from the inner wall surface of the via hole.

Claim 10 (Original): An electronic component according to claim 9, wherein the core material is formed of glass cloth.

Claim 11 (Original): An electronic component comprising:
a base material having a conductor layer on at least one surface thereof;
a via hole formed through laser irradiation from the other surface side of the base material;
a protrusion protruding from an inner wall surface of the via hole; and
a conductor part which forms an anchor structure together with the protrusion formed in the via hole to be thereby prevented from being detached from the protrusion.

Claim 12 (Original): An electronic component according to Claim 11, wherein the protrusion is formed by a core material, which is included in the basic material, protruding from the inner wall surface of the via hole.

Claim 13 (Original): An electronic component according to claim 12, wherein the core material is formed of glass cloth.